



TSMC Board of Directors Meeting Resolutions

HSINCHU, Taiwan, R.O.C., June 5, 2024 – The TSMC (TWSE: 2330, NYSE: TSM) Board of Directors today held a meeting, which passed the following resolutions:

1. To meet long-term capacity plans based on market demand forecasts and technology development roadmap, the Board approved capital appropriations of approximately US\$17,356.20 million for purposes including: 1) Installation and upgrade of advanced technology capacity; 2) Installation and upgrade of advanced packaging, mature and/or specialty technology capacity; 3) Fab construction, and installation of fab facility systems.
2. Approved the capital injection of not more than US\$5 billion to TSMC Global Ltd., a wholly-owned subsidiary of TSMC, for the purpose of reducing foreign exchange hedging costs.
3. Approved a total donation of not more than NT\$4 billion to National Taiwan University (NTU), National Yang Ming Chiao Tung University (NYCU), National Tsing Hua University (NTHU), National Cheng Kung University (NCKU) and selected senior high schools and girls' senior high schools in Taiwan to enhance long-term semiconductor research, education and talent cultivation.
4. In order to offset the dilution from the increase of outstanding shares due to Employee Restricted Stock Awards (RSAs) issuance, the Board approved a share buyback program for TSMC to buy back 3,249,000 common shares on Taiwan Stock Exchange.

About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,895 products for 528 customers in 2023 by providing broadest range of advanced, specialty and advanced packaging technology services. The Company is headquartered in Hsinchu, Taiwan. For more information please visit <https://www.tsmc.com>.



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